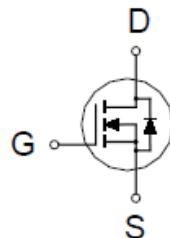
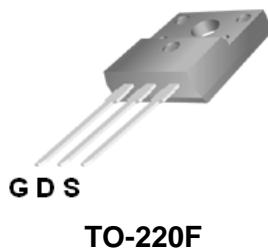


# P8010BTF

## N-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
100V	85mΩ @ $V_{GS} = 10V$	11A



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current $T_C = 25^\circ C$	$I_D$	11	A
		7	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	35	A
Avalanche Current	$I_{AS}$	14	
Avalanche Energy	$E_{AS}$	10	mJ
Power Dissipation $T_C = 25^\circ C$	$P_D$	24	W
		9.6	
Junction & Storage Temperature Range	$T_J, T_{stg}$	-55 to 150	°C

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$	5.2	62.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$			

<sup>1</sup>Pulse width limited by maximum junction temperature.

# P8010BTF

## N-Channel Enhancement Mode MOSFET

### ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)

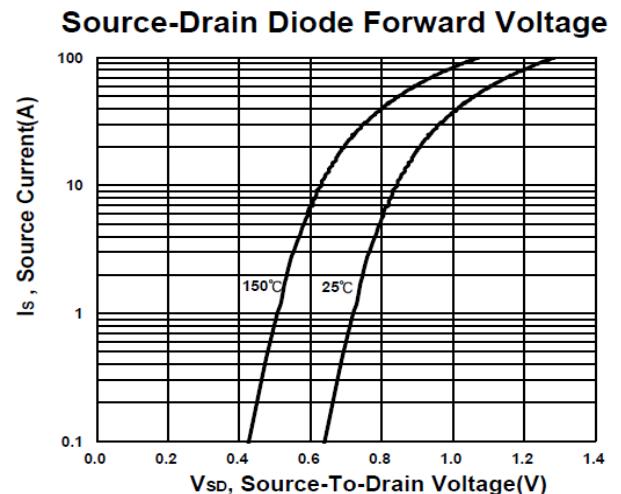
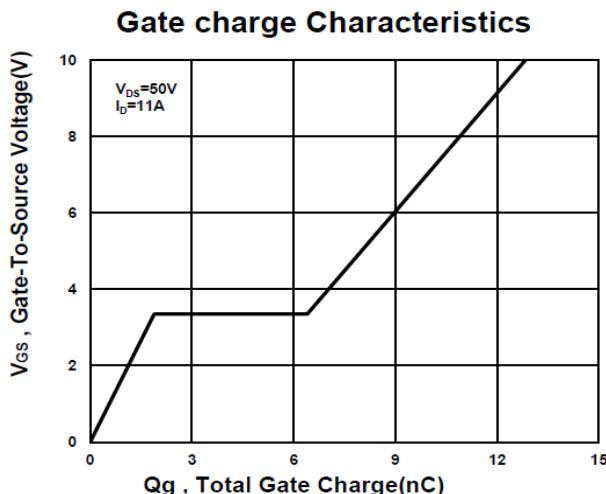
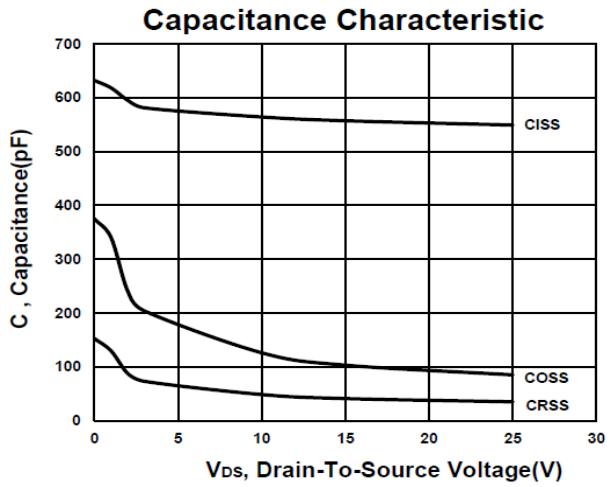
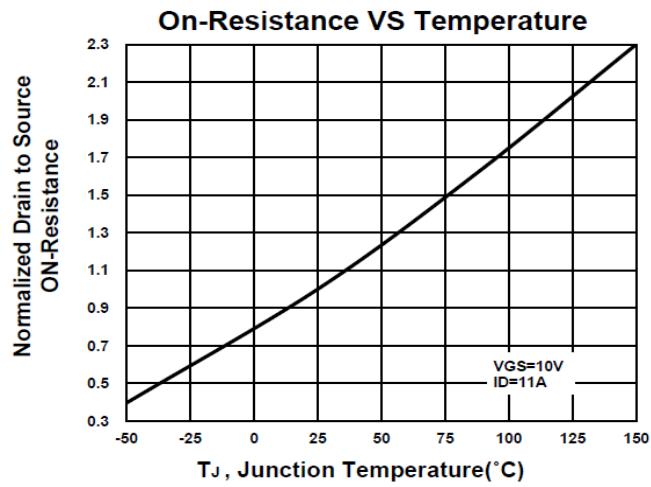
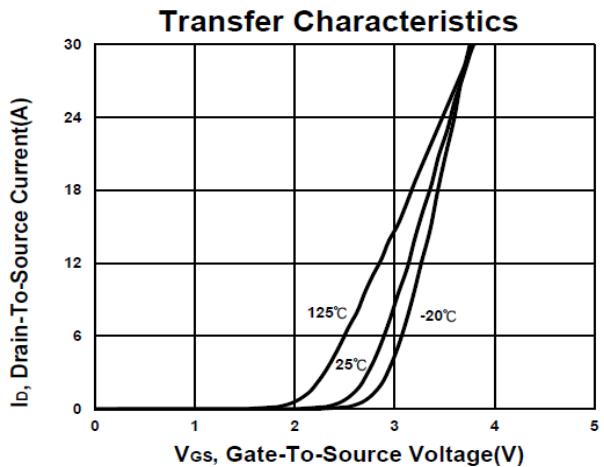
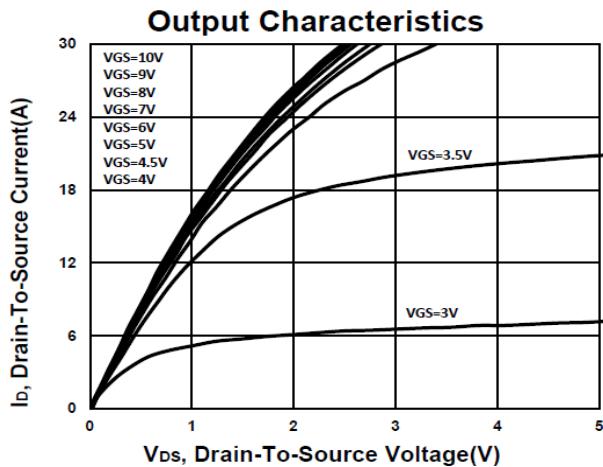
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.3	1.8	2.3	
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 80\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
		$V_{\text{DS}} = 80\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
Drain-Source On-State Resistance <sup>1</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$		61	95	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 11\text{A}$		59	85	
Forward Transconductance <sup>1</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 10\text{V}, I_D = 11\text{A}$		28		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$		550		pF
Output Capacitance	$C_{\text{oss}}$			86		
Reverse Transfer Capacitance	$C_{\text{rss}}$			36		
Gate Resistance	$R_g$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		1.1		$\Omega$
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 11\text{A}$		12.9		nC
Gate-Source Charge <sup>2</sup>	$Q_{\text{gs}}$			2		
Gate-Drain Charge <sup>2</sup>	$Q_{\text{gd}}$			4.6		
Turn-On Delay Time <sup>2</sup>	$t_{\text{d(on)}}$	$V_{\text{DS}} = 40\text{V}, I_D \geq 11\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		11		nS
Rise Time <sup>2</sup>	$t_r$			48		
Turn-Off Delay Time <sup>2</sup>	$t_{\text{d(off)}}$			80		
Fall Time <sup>2</sup>	$t_f$			73		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ\text{C}</math>)</b>						
Continuous Current	$I_S$				11	A
Forward Voltage <sup>1</sup>	$V_{\text{SD}}$	$I_F = 11\text{A}, V_{\text{GS}} = 0\text{V}$			1.1	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F = 11\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		33		nS
Reverse Recovery Charge	$Q_{\text{rr}}$			47		nC

<sup>1</sup>Pulse test : Pulse Width  $\leq 300\ \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

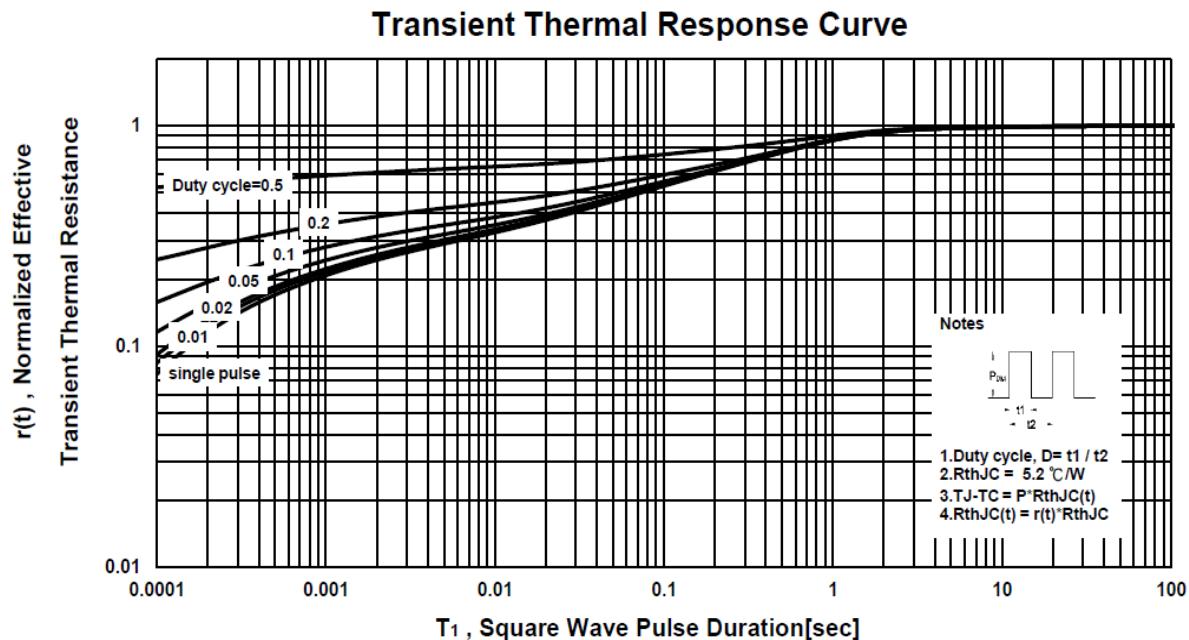
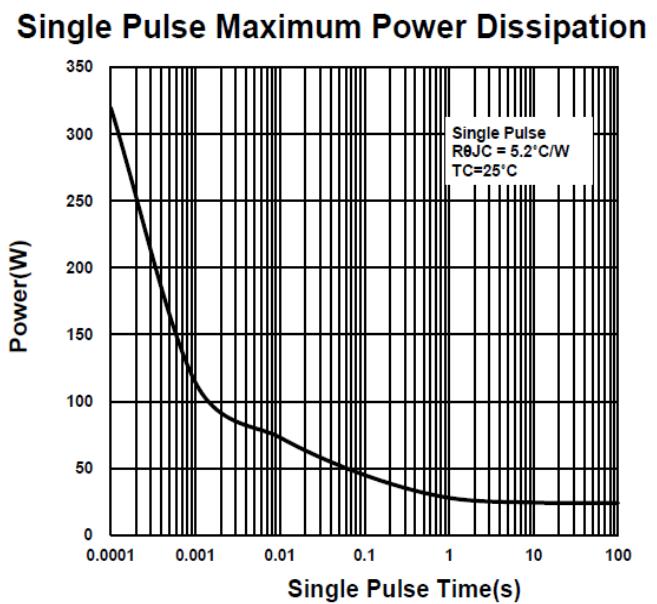
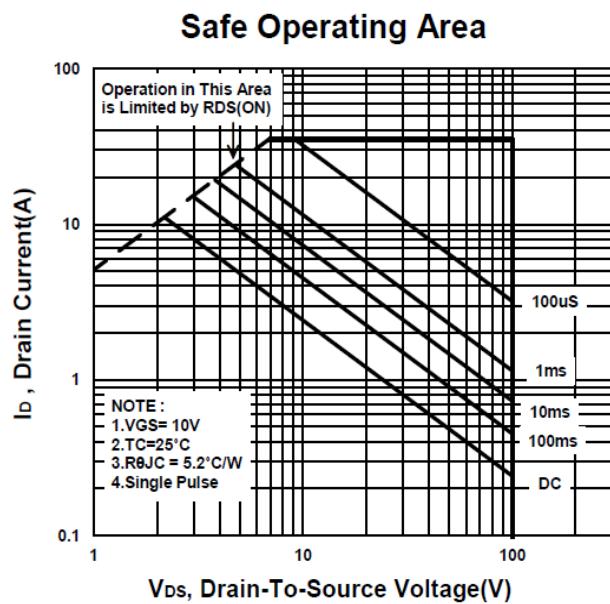
# P8010BTF

## N-Channel Enhancement Mode MOSFET



## P8010BTF

### N-Channel Enhancement Mode MOSFET



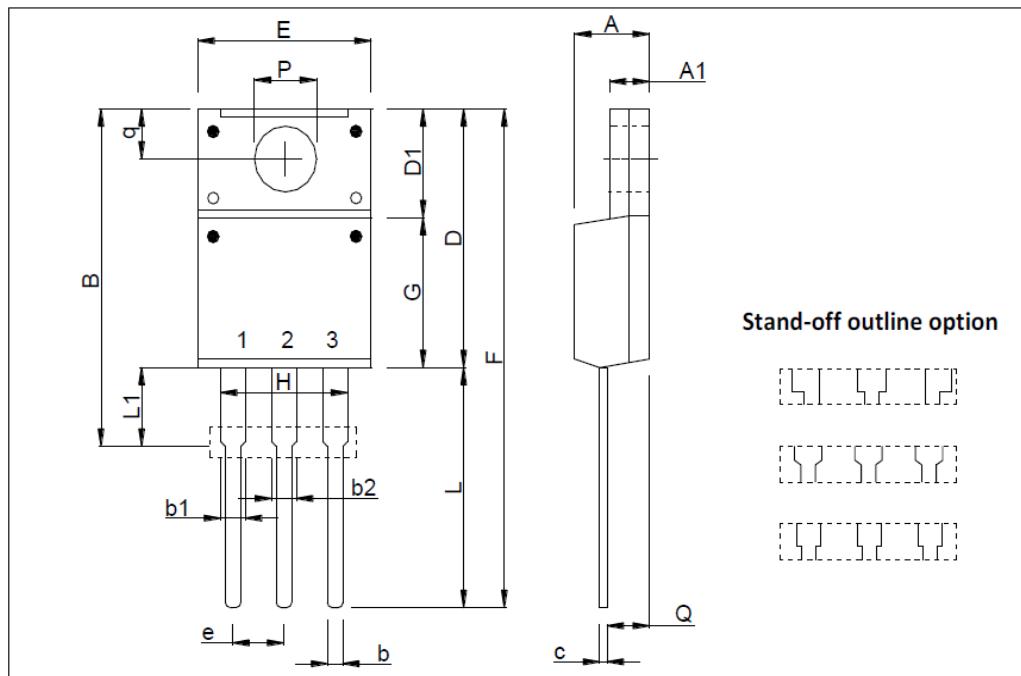
## P8010BTF

### N-Channel Enhancement Mode MOSFET

#### Package Dimension

#### TO-220F (3-Lead) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.4		4.93	e	2.34		2.74
A1	2.34		3.1	F	27.2		30.6
B	18.8		20	G	7.7		9.39
b	0.65		1	H	6.18		6.82
b1	0.93		1.6	L	12.7		14.2
b2	0.95		1.6	L1	2.88		3.7
c	0.4		1	P	2.98		3.7
D	13.5		16.4	Q	2.3		2.96
D1	6.48		6.95	q	3.1		3.8
E	9.8		10.4				

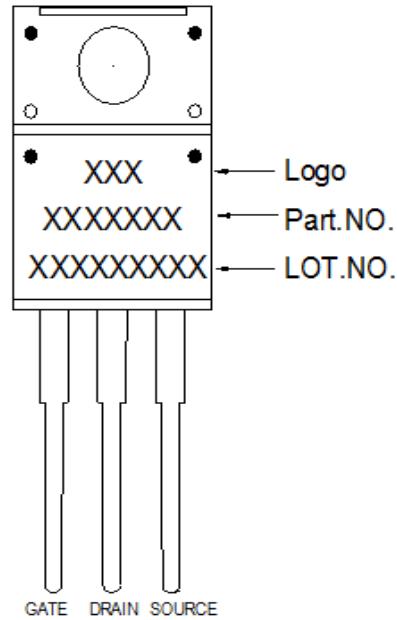


\*因各家封装模具不同而外观略有差异，不影响电性及Layout。

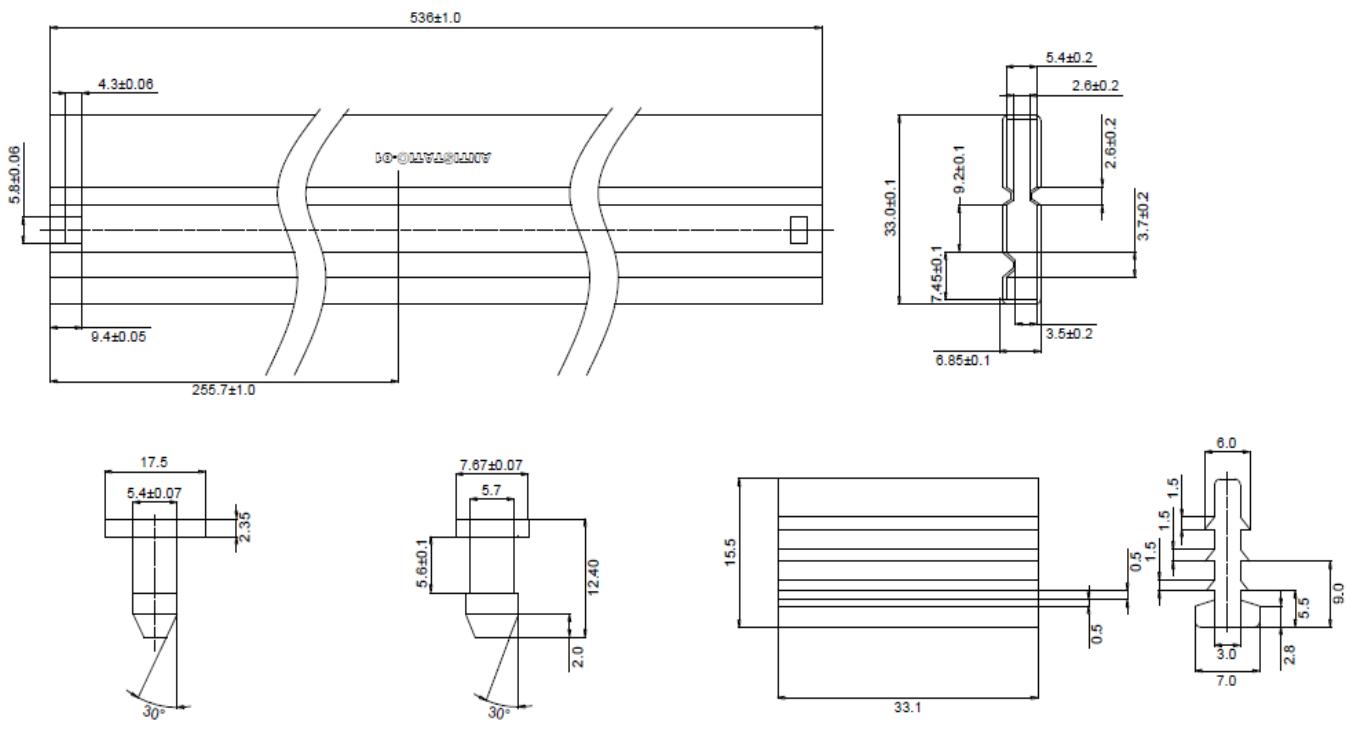
## P8010BTF

### N-Channel Enhancement Mode MOSFET

#### A. Marking Information



#### B. Tape&Reel Information: 50pcs/Tube(2000pcs/Box)

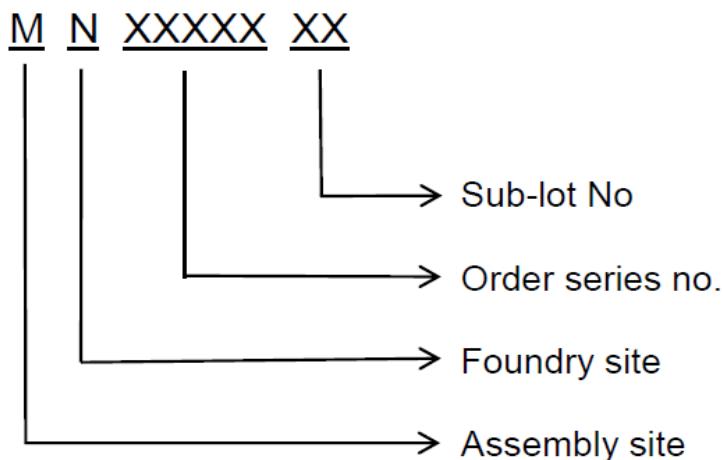


## P8010BTF

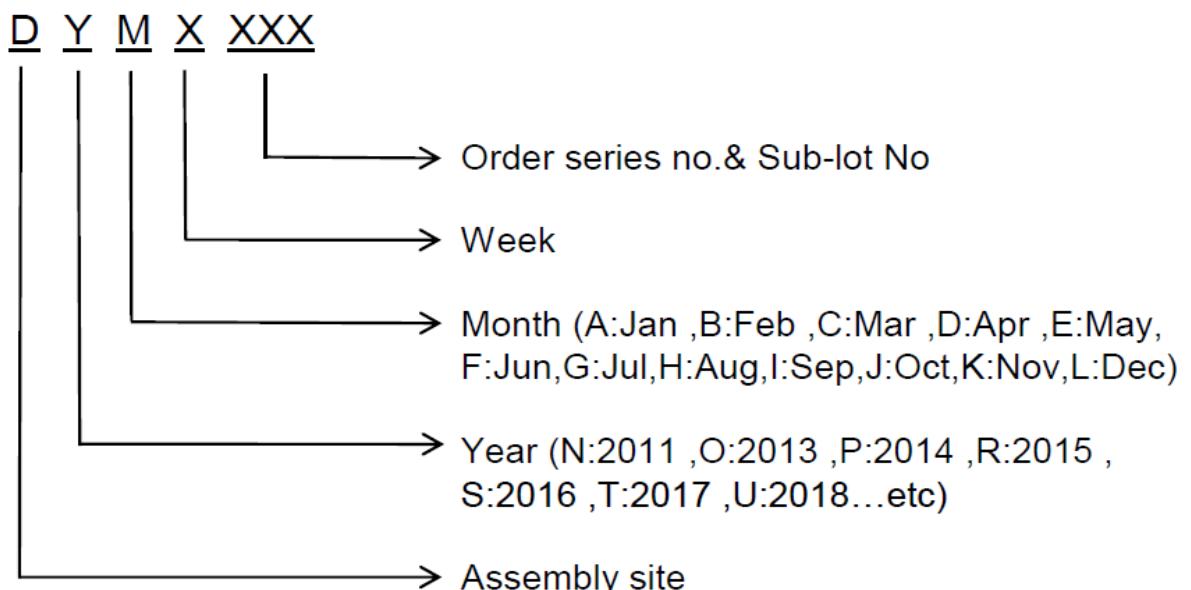
### N-Channel Enhancement Mode MOSFET

#### C. Lot No.&Date Code rule

##### 1. Lot No.



##### 2. Date Code



## P8010BTF

### N-Channel Enhancement Mode MOSFET

#### D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm			
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)			
3	U-NIKC	Height: 4 mm			
4	Package	Height: 2 mm			
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12			
6	Device	Height: 3 mm (Max: 16 Digit)			
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot			
8	D/C	Height: 3 mm (Max: 7 Digit)			
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed			
10	RoHS label	 long axis: 12 mm      minor axis: 6 mm bottom color: White Font color: Black      Font style: Arial			
11	Halogen Free label	 Diameter: 10 mm      bottom color: Green Font color: Black      Font style: Arial			
12	Scan information	Device / Lot / D/C / QTY , Insert “ / ” between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least			